Express-KL/KLE

**COM Express Basic Size Type 6 Module with 7th Gen Intel® Core™, Intel® Xeon® Processor**

**Features**

- 7th Gen Intel® Core™, Intel® Xeon® Processor
- Up to 32 GB Dual Channel DDR4 at 1867/2133 MHz (supports both ECC and non-ECC memory)
- 3x DDI channels, 1x LVDS (or 4 lanes eDP) supports up to 3 independent displays
- 8x PCIe x1 (Gen3) and 1x PCIe x16 (Gen3)
- GbE, 4x SATA 6 Gb/s, 4x USB 3.0 and 4x USB 2.0
- Supports Smart Embedded Management Agent (SEMA®) functions
- Extreme Rugged operating temperature: -40°C to +85°C (build option)

**Specifications**

- **Core System**
  - CPU
    - Mobile Intel® Xeon®, Core™ Processors - 14nm
      - Xeon® E3-1505M v6 3.0/4.0GHz (Turbo), 45W (4C/GT2)
      - Xeon® E3-1505L v6 2.2/3.0GHz (Turbo), 25W (4C/GT2)
      - Core™ i7-7820EQ 2.9/3.7GHz (Turbo), 45W (4C/GT2)
      - Core™ i5-7440EQ 2.9/3.6GHz (Turbo), 45W (4C/GT2)
      - Core™ i3-7100E 2.9GHz (no Turbo), 35W (2C/GT2)
      - Core™i3-7102E 2.1GHz (no Turbo), 25W (2C/GT2)
      - Note: Availability of the features may vary between processor SKUs.
  - Memory
    - Dual channel 1867/2133 MHz DDR4 memory up to 32GB in dual SODIMM sockets (ECC/non-ECC support dependent on selected CPU/PCH)
  - Embedded BIOS
    - AMI EFI with CMOS backup in 16MB SPI BIOS with Intel® AMT 11.6 support
  - Cache
    - 8MB for Xeon® and Core™ i7, 6MB for Core™ i5, 3MB for Core™ i3
  - PCH
    - CM238 (supports ECC memory, Intel AMT)
    - QM175 (supports non-ECC, Intel AMT)
    - HM175 (supports non-ECC, no Intel AMT support)
  - Expansion Busses
    - PCIe x16 or 2 PCIe x8 or 2 PCIe x8 with 2 PCIe x4 (Gen3)
    - 6 PCI Express x1 (Gen3); AB connector, Lanes 0/1/2/3/4/5
    - 2 PCI Express x2 (Gen3); CD connector, Lanes 6/7
    - LPC bus, SMBus (system), I²C (user)

- **Debug Headers**
  - 40-pin flat cable connector for use with DB-40 debug module providing BIOS POST code LED, BMC access, SPI BIOS flashing, power testpoints, debug LEDs
  - 60-pin XDP header for ICE debug of CPU/chipset

- **Video**
  - **GPU Feature Support**
    - Intel® Generation 9 LP Graphics Core Architecture, supporting 3 independent and simultaneous display combinations of DisplayPort/HDMI/LVDS or eDP outputs
  - **Hardware encode/transcode**
    - HD content (including HEVC) DirectX 12, DirectX 11.2, DirectX 11.1, DirectX 11, DirectX 10.1, DirectX 10, DirectX 9 support OpenGL 4.4/4.3 and ES 2.0 support
    - OpenCL 2.1, 2.0/1.2 support

- **Digital Display Interface**
  - DDI1/2/3 supporting DisplayPort/HDMI/DVI
  - **LVDS**
    - Single/dual channel 18/24-bit LVDS from eDP-to-LVDS IC
  - **eDP**
    - 4 lane support optional, in place of LVDS

- **Audio**
  - **Chipset**
    - Intel® HD Audio integrated in chipset
  - **Audio Codec**
    - located on carrier Express-BASE6 (ALC886 standard supported)

- **Ethernet**
  - **Chipset**
    - Intel® MACPHY: i219LM/V (LM with AMT 11.0 support)
  - Interface: 10/100/1000 GbE connection

Note: “build option” indicates an alternative BOM configuration to support additional or alternative functions that are not available on the standard product.

Be aware that these “build option” part numbers will need to be newly created and this will result in production lead times.
Specifications

● I/O Interfaces
  USB: 4x USB v. 3.0 (USB 0,1,2,3) and 4x USB 2.0 (USB 4,5,6,7)
  SATA: Four ports SATA 6Gb/s (SATA0,1,2,3)
  Serial: 2 UART ports with console redirection
  GPIO: 4 GPO and 4 GPI

● Super I/O
  Supported on carrier if needed (standard support for W83627DHG-P)

● TPM
  Chipset: Infineon
  Type: TPM 2.0

● Power
  Standard Input: ATX = 12V±5% / 5Vsb ±5% or AT = 12V±5%
  Wide Input: ATX = 8.5-20 V / 5Vsb ±5% or AT = 8.5 ~20V (Standard temp. only)
  Management: ACPI 5.0 compliant, Smart Battery support
  Power States: C1-C6, S0, S1, S3, S4, S5, SS ECO mode (Wake-on-USB S3/S4, WOL S3/S4/SS)
  ECO mode: Supports deep SS mode for power saving

● Operating Systems
  Standard Support
  Windows 10 64-bit, Linux 64-bit, VxWorks
  Extended Support (BSP)
  Linux 64-bit, VxWorks

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Be aware that these "build option" part numbers will need to be newly created and this will result in production lead times.

● Mechanical and Environmental
  Form Factor: PICMG COM.0, Rev 2.1 Type 6
  Dimension: Basic size, 125 mm x 95 mm

  Operating Temperature
  Standard: 0°C to 60°C
  Extreme Rugged: -40°C to +85°C (build option for 25W TDP SKUs)

  Humidity
  5-90% RH operating, non-condensing
  5-95% RH storage (and operating with conformal coating)

  Shock and Vibration
  IEC 60068-2-64 and IEC-60068-2-27
  MIL-STD-202F, Method 213B, Table 213-I, Condition A and Method 214A, Table 214-I, Condition D

  HALT
  Thermal Stress, Vibration Stress, Thermal Shock and Combined Test

● Intelligent Middleware
  SEMA®
  Local management, control of embedded computer systems
  Extended EAPI for monitoring, controlling and analytics applications
  Multiple OS support and across platforms (x86, ARM)
Ordering Information

- **Express-KLE-E3-1505M v6**
  Basic Size COM Express® Type 6 module with Intel® Xeon® E3-1505M v6 and GT2 level graphics, CM238 chipset

- **Express-KLE-E3-1505L v6**
  Basic Size COM Express® Type 6 module with Intel® Xeon® E3-1505M v6 and GT2 level graphics, CM238 chipset

- **Express-KL-i7-7820EQ**
  Basic Size COM Express® Type 6 module with Intel® Xeon® i7-7820EQ and GT2 level graphics, CM238 chipset

- **Express-KL-i5-7440EQ**
  Basic Size COM Express® Type 6 module with Intel® Core™ i5-7440EQ and GT2 level graphics, CM238 chipset

- **Express-KL-i5-7442EQ**
  Basic Size COM Express® Type 6 module with Intel® Core™ i5-7442EQ and GT2 level graphics, CM238 chipset

- **Express-KL-i3-7100E**
  Basic Size COM Express® Type 6 module with Intel® Core™ i3-7100E and GT2 level graphics, CM238 chipset

- **Express-KL-i3-7102E**
  Basic Size COM Express® Type 6 module with Intel® Core™ i3-7102E and GT2 level graphics, CM238 chipset

Accessories

**Heat Spreaders**

- **HTS-SL-B**
  Heatspreader for Express-SL with threaded standoffs for bottom mounting

- **HTS-SL-BT**
  Heatspreader for Express-SL with through hole standoffs for top mounting

**Passive Heatsinks**

- **THS-SL-BL**
  Low profile heatsink for Express-SL with threaded standoffs for bottom mounting

- **THS-SL-BT**
  Low profile heatsink for Express-SL with through hole standoffs for top mounting

- **THS-SC-BL**
  High profile heatsink for Express-SL with threaded standoffs for top mounting

**Active Heatsink**

- **TSF-SL-BL**
  High profile heatsink with Fan for Express-KL with threaded standoffs for bottom mounting

**Starter Kit**

- **Starterkit-COM Express 6 PLUS**
  COM Express formfactor starter kit with Express-BASE6 board, power supply, and accessory kit